Closed Topic Search

Enter terms
Search

Reset Sort By: Relevancy (descending)

- Relevancy (ascending)
- Title (ascending)
- Open Date (descending)
- Close Date (descending)
- Release Date (descending)

NOTE: The Solicitations and topics listed on this site are copies from the various SBIR agency solicitations and are not necessarily the latest and most up-to-date. For this reason, you should visit the respective agency SBIR sites to read the official version of the solicitations and download the appropriate forms and rules.

Displaying 5 result(s)

1. DMEA122-001: High Speed, High Resolution X-ray System for Inspecting Integrated Circuits

   Release Date: 04-24-2012Open Date: 05-24-2012Due Date: 06-27-2012Close Date: 06-27-2012

   OBJECTIVE: Develop an affordable x-ray microscope system for use in performing integrated circuit (IC) reverse engineering. DESCRIPTION: X-ray microscopy using a synchrotron as the x-ray source has been demonstrated to be an extremely valuable tool in the performance of high throughput integrated circuit evaluation and reverse engineering efforts. However, synchrotron x-ray sources are prohi ...

   SBIR Defense Microelectronics Activity

2. DMEA132-001: Miniaturized RF over Fiber

   Release Date: 04-24-2013Open Date: 05-24-2013Due Date: 06-26-2013Close Date: 06-26-2013

   OBJECTIVE: Design and prototype a capability to use fiber optic cable to simultaneously distribute power (i.e power over fiber) while providing full duplex information flow. The capability will allow miniature microwave system components to be distributed over a relatively long distance (i.e. 30 meters or more) via fiber optics. For example, a processing node (within a microwave system) provid ...

   SBIR Defense Microelectronics Activity

3. DMEA132-002: High Resolution Three-Dimensional Digital Reconstruction of Integrated Circuits

   Release Date: 04-24-2013Open Date: 05-24-2013Due Date: 06-26-2013Close Date: 06-26-2013

   OBJECTIVE: Develop a system for the accurate identification and analysis of semiconductor materials with integrated, high-resolution imaging capability for the three-dimensional digital reconstruction of integrated circuits (ICs). DESCRIPTION: As semiconductor geometries continue to diminish, so too does the applicability of traditional sample preparation tools. As the thickness of metal l ...

   SBIR Defense Microelectronics Activity

4. DMEA13B-001: Electrochemical Micro-Capacitors Utilizing Carbon Nanostructures

   Release Date: 07-26-2013Open Date: 08-26-2013Due Date: 09-25-2013Close Date: 09-25-2013

   TECHNOLOGY AREAS: Materials/Processes, Electronics The technology within this topic is restricted under the International Traffic in Arms Regulation (ITAR), which controls the export and import of defense-related material and services. Offerors must disclose any proposed use of foreign nationals, their country of origin, and what tasks each would accomplish in the statement of work in accordan ...

   STTR Department of DefenseDefense Microelectronics Activity

5. DMEA15B-001: Optimized Scintillator for High Resolution X-ray Imaging at 9keV

Release Date: 04-24-2015Open Date: 05-26-2015Due Date: 06-24-2015Close Date: 06-24-2015

Rapid Integrated Circuit (IC) inspection using x-ray microscopy requires novel x-ray scintillating materials with high efficiency and high spatial resolution. Current scintillator materials, such as Cesium Iodide (CsI), suffer from a trade-off between efficiency and spatial resolution. Novel materials with higher stopping power and light yields are necessary to address the stringent requirements o ...

STTR Defense Microelectronics ActivityDepartment of Defense

jQuery(document).ready(function() { (function ($) { $('#edit-keys').attr("placeholder", 'Search Keywords'); $('span.ext').hide(); })(jQuery); });